

Power MOSFET

200 mAmps, 50 Volts

N-Channel SC-88

Typical applications are dc-dc converters, power management in portable and battery-powered products such as computers, printers, PCMCIA cards, cellular and cordless telephones.

- Low Threshold Voltage ($V_{GS(th)}$: 0.5V...1.5V) makes it ideal for low voltage applications
- Miniature SC-88 Surface Mount Package saves board space
- Pb-Free Package May be Available. The G-Suffix Denotes a Pb-Free Lead Finish
- ESD Protected: 1500V

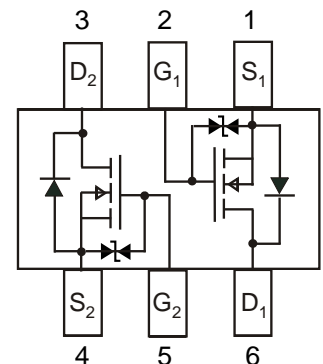
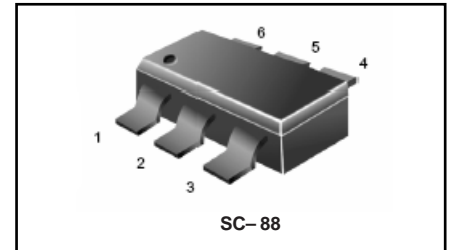
ORDERING INFORMATION

Device	Package	Shipping
LBSS139DW1T1G	SC-88	3000 Tape & Reel
LBSS139DW1T3G	SC-88	10000 Tape & Reel

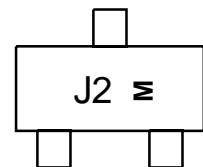
MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Rating	Symbol	Value	Unit
Drain-to-Source Voltage	V_{DSS}	50	Vdc
Gate-to-Source Voltage – Continuous	V_{GS}	± 20	Vdc
Drain Current – Continuous @ $T_A = 25^\circ\text{C}$ – Pulsed Drain Current ($t_p \leq 10 \mu\text{s}$)	I_D I_{DM}	200 800	mA
Total Power Dissipation @ $T_A = 25^\circ\text{C}$	P_D	380	mW
Operating and Storage Temperature Range	T_J, T_{stg}	- 55 to 150	$^\circ\text{C}$
Thermal Resistance – Junction-to-Ambient	$R_{\theta JA}$	328	$^\circ\text{C/W}$
Maximum Lead Temperature for Soldering Purposes, for 10 seconds	T_L	260	$^\circ\text{C}$

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MARKING DIAGRAM & PIN ASSIGNMENT



J2 = Device Code
M = Month Code

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ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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OFF CHARACTERISTICS

Drain-to-Source Breakdown Voltage ($V_{GS} = 0\text{ Vdc}$, $I_D = 250\ \mu\text{Adc}$)	$V_{(BR)DSS}$	50	–	–	Vdc
Zero Gate Voltage Drain Current ($V_{DS} = 25\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$) ($V_{DS} = 50\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$)	I_{DSS}	– –	– –	0.1 0.5	μAdc
Gate-Source Leakage Current ($V_{GS} = \pm 20\text{ Vdc}$, $V_{DS} = 0\text{ Vdc}$)	I_{GSS}	–	–	± 10	μAdc

ON CHARACTERISTICS (Note 1.)

Gate-Source Threshold Voltage ($V_{DS} = V_{GS}$, $I_D = 1.0\text{ mAdc}$)	$V_{GS(th)}$	0.5	–	1.5	Vdc
Static Drain-to-Source On-Resistance ($V_{GS} = 2.75\text{ Vdc}$, $I_D < 200\text{ mAdc}$, $T_A = -40^\circ\text{C}$ to $+85^\circ\text{C}$) ($V_{GS} = 5.0\text{ Vdc}$, $I_D = 200\text{ mAdc}$)	$r_{DS(on)}$	– –	5.6 –	10 3.5	Ohms
Forward Transconductance ($V_{DS} = 25\text{ Vdc}$, $I_D = 200\text{ mAdc}$, $f = 1.0\text{ kHz}$)	g_{fs}	100	–	–	mmhos

DYNAMIC CHARACTERISTICS

Input Capacitance	($V_{DS} = 25\text{ Vdc}$, $V_{GS} = 0$, $f = 1\text{ MHz}$)	C_{iss}	–	22.8	–	pF
Output Capacitance	($V_{DS} = 25\text{ Vdc}$, $V_{GS} = 0$, $f = 1\text{ MHz}$)	C_{oss}	–	3.5	–	
Transfer Capacitance	($V_{DG} = 25\text{ Vdc}$, $V_{GS} = 0$, $f = 1\text{ MHz}$)	C_{rss}	–	2.9	–	

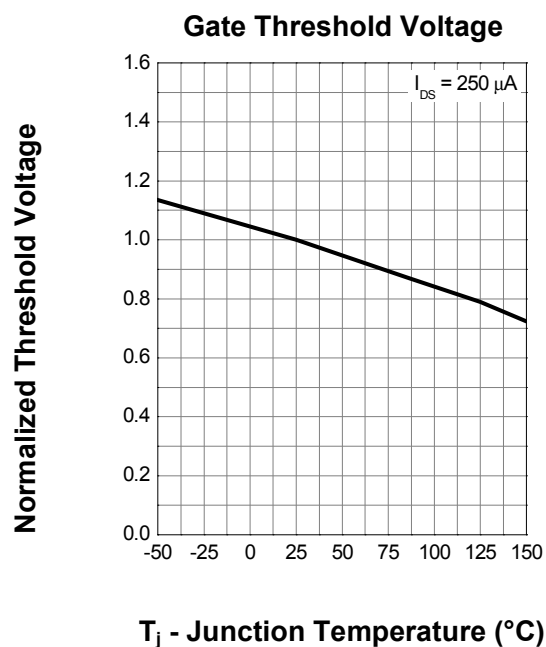
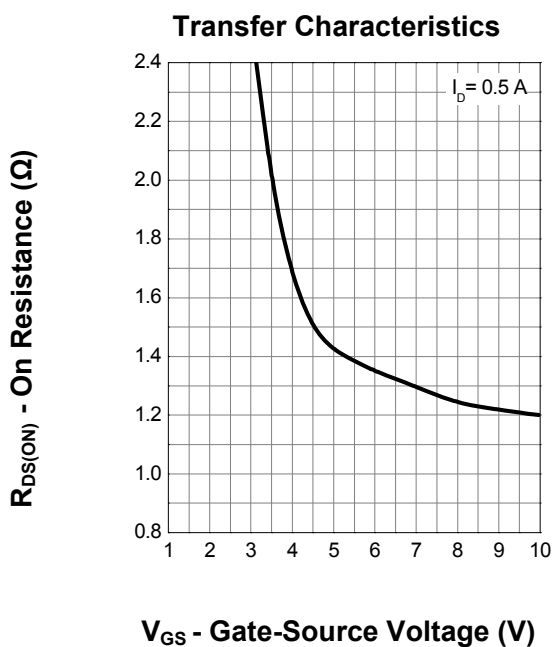
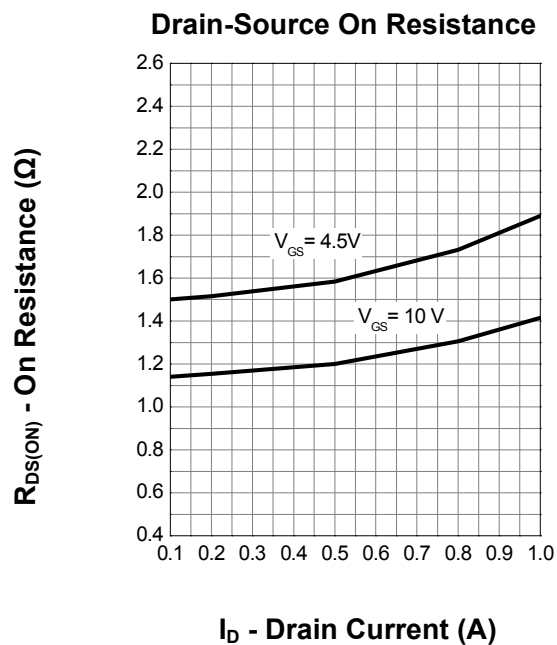
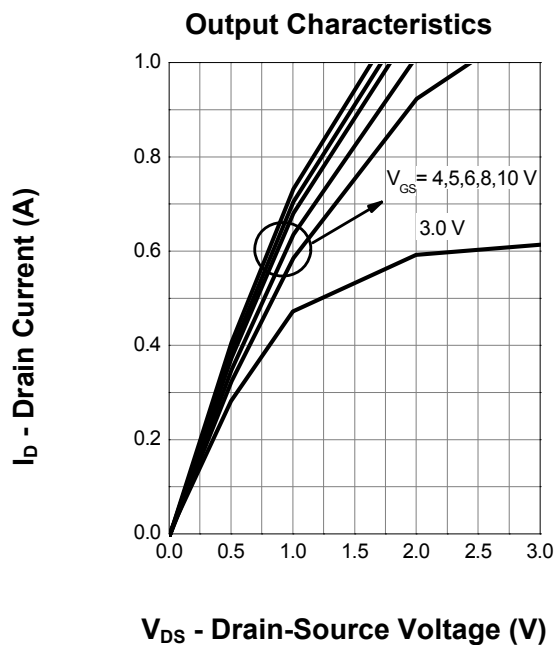
SWITCHING CHARACTERISTICS (Note 2.)

Turn-On Delay Time	($V_{DS} = 30\text{ Vdc}$, $I_{DS} = 0.5\text{ Adc}$,)	$t_{d(on)}$	–	3.8	–	ns
Turn-Off Delay Time		$t_{d(off)}$	–	19	–	

1. Pulse Test: Pulse Width $\leq 300\ \mu\text{s}$, Duty Cycle $\leq 2\%$.
2. Switching characteristics are independent of operating junction temperature.

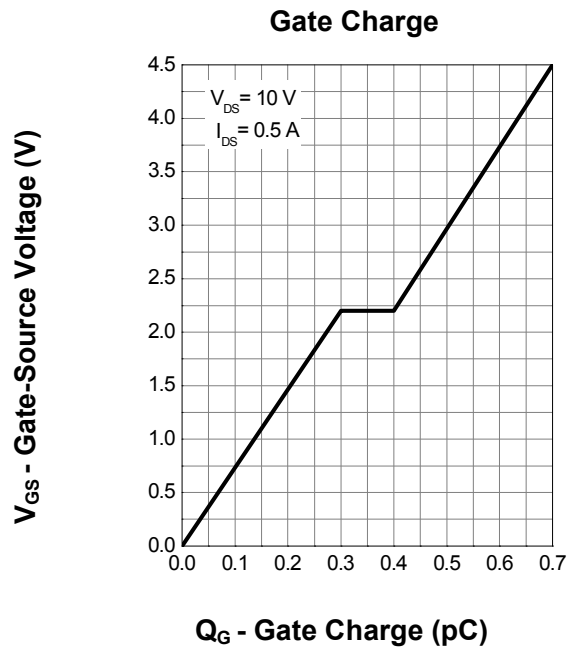
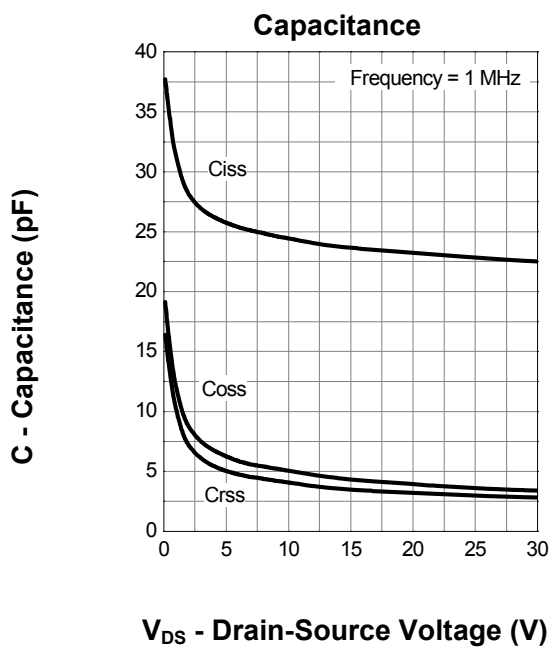
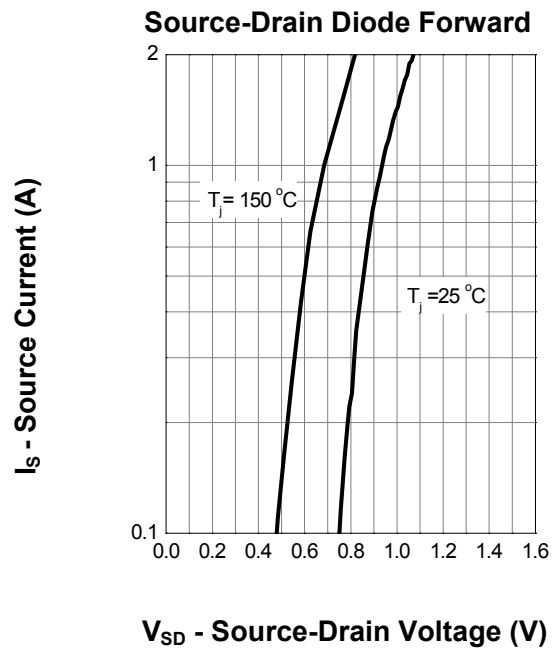
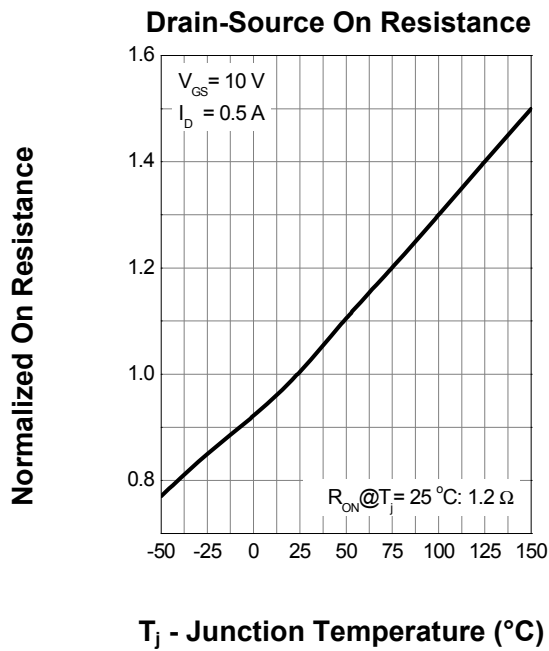
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TYPICAL ELECTRICAL CHARACTERISTICS

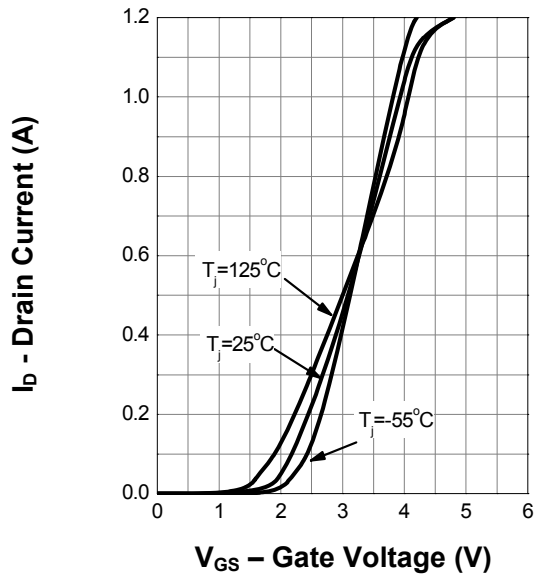
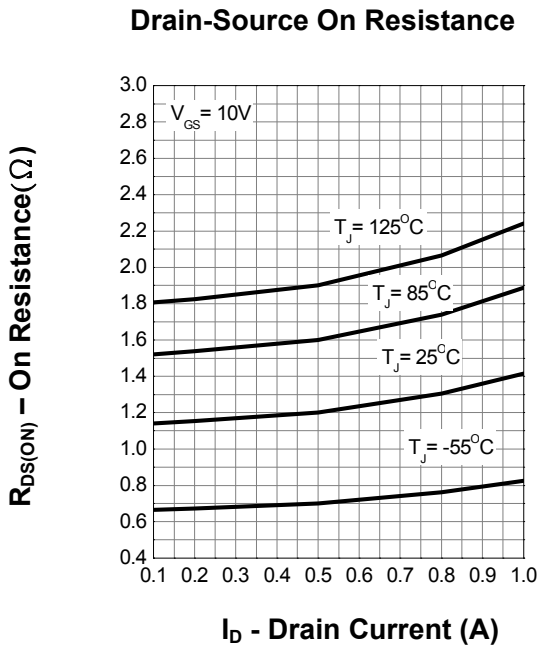
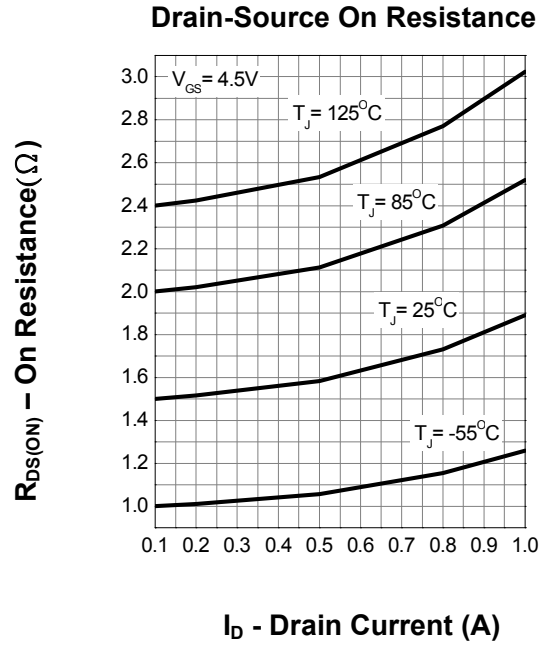
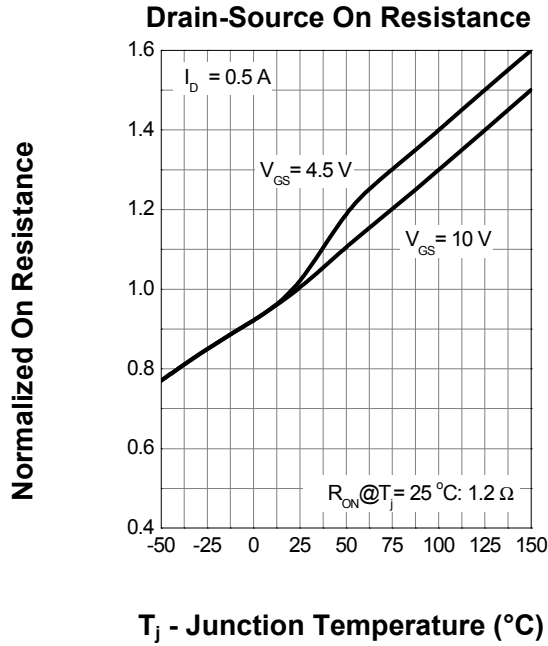


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TYPICAL ELECTRICAL CHARACTERISTICS

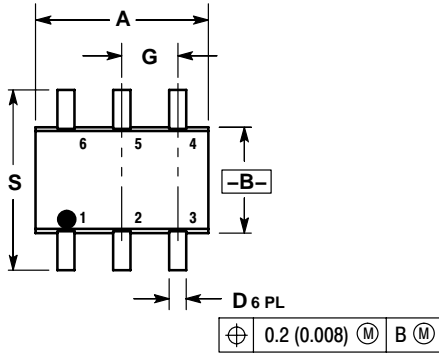


TYPICAL ELECTRICAL CHARACTERISTICS



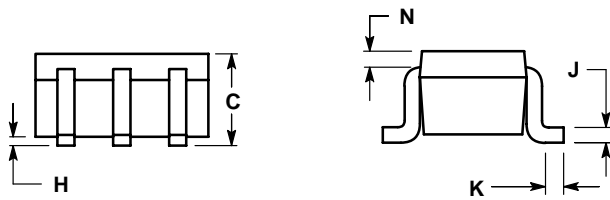
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SC-88



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.071	0.087	1.80	2.20
B	0.045	0.053	1.15	1.35
C	0.031	0.043	0.80	1.10
D	0.004	0.012	0.10	0.30
G	0.026 BSC		0.65 BSC	
H	---	0.004	---	0.10
J	0.004	0.010	0.10	0.25
K	0.004	0.012	0.10	0.30
N	0.008 REF		0.20 REF	
S	0.079	0.087	2.00	2.20



- STYLE 1:
 PIN 1. EMITTER 2
 2. BASE 2
 3. COLLECTOR 1
 4. EMITTER 1
 5. BASE 1
 6. COLLECTOR 2

SOLDERING FOOTPRINT*

